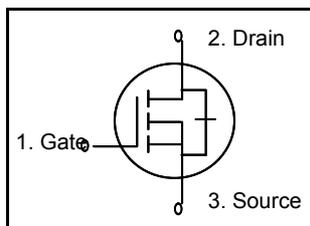


N-Channel MOSFET

Features

- High ruggedness
- $R_{DS(on)}$ (Max 2.5)@ $V_{GS}=10V$
- Gate Charge (Typical 25nC)
- Improved dv/dt Capability
- 100% Avalanche Tested

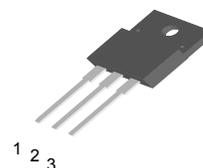


$BV_{DSS} = 600V$
 $R_{DS(ON)} = 2.5 \text{ ohm}$
 $I_D = 4A$

General Description

This N-channel enhancement mode field-effect power transistor using D&I semiconductor's advanced planar stripe, DMOS technology intended for off-line switch mode power supply. Also, especially designed to minimize $r_{ds(on)}$ and high rugged avalanche characteristics. The TO-220F (Isolated) pkg is well suited for adaptor power unit and power inverter application.

TO-220F



Absolute Maximum Ratings

Symbol	Parameter	Value	Units
V_{DSS}	Drain to Source Voltage	600	V
I_D	Continuous Drain Current(@ $T_C = 25^\circ C$)*	4	A
	Continuous Drain Current(@ $T_C = 100^\circ C$)*	2.5	A
I_{DM}	Drain Current Pulsed (Note 1)	16	A
V_{GS}	Gate to Source Voltage	± 30	V
E_{AS}	Single Pulsed Avalanche Energy (Note 2)	262	mJ
E_{AR}	Repetitive Avalanche Energy (Note 1)	3.3	mJ
dv/dt	Peak Diode Recovery dv/dt (Note 3)	4.5	V/ns
P_D	Total Power Dissipation(@ $T_C = 25^\circ C$)	33	W
	Derating Factor above $25^\circ C$	0.26	W/ $^\circ C$
T_{STG}, T_J	Operating Junction Temperature & Storage Temperature	- 55 ~ 150	$^\circ C$
T_L	Maximum Lead Temperature for soldering purpose, 1/8 from Case for 5 seconds.	300	$^\circ C$

* Ensure that the channel temperature does not exceed 150

Thermal Characteristics

Symbol	Parameter	Value			Units
		Min.	Typ.	Max.	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case	-	-	3.79	$^\circ C/W$
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	-	-	62.5	$^\circ C/W$

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Electrical Characteristics ($T_C = 25\text{ }^\circ\text{C}$ unless otherwise noted)

Symbol	Parameter	Test Conditions	Min	Typ	Max	Units
Off Characteristics						
BV_{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A$	600	-	-	V
BV_{DSS}/T_J	Breakdown Voltage Temperature coefficient	$I_D = 250\mu A$, referenced to $25\text{ }^\circ\text{C}$	-	0.68	-	$V/^\circ\text{C}$
I_{DSS}	Drain-Source Leakage Current	$V_{DS} = 600V, V_{GS} = 0V$	-	-	10	μA
		$V_{DS} = 480V, T_C = 125\text{ }^\circ\text{C}$	-	-	100	μA
I_{GSS}	Gate-Source Leakage, Forward	$V_{GS} = 30V, V_{DS} = 0V$	-	-	100	nA
	Gate-source Leakage, Reverse	$V_{GS} = -30V, V_{DS} = 0V$	-	-	-100	nA
On Characteristics						
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	2.0	-	4.0	V
$R_{DS(on)}$	Static Drain-Source On-state Resistance	$V_{GS} = 10V, I_D = 2.0A$	-	2.0	2.5	
Dynamic Characteristics						
C_{iss}	Input Capacitance	$V_{GS} = 0V, V_{DS} = 25V, f = 1\text{MHz}$	-	520	650	pF
C_{oss}	Output Capacitance		-	135	195	
C_{rss}	Reverse Transfer Capacitance		-	280	400	
Dynamic Characteristics						
$t_{d(on)}$	Turn-on Delay Time	$V_{DD} = 300V, I_D = 4.0A, R_G = 25$ see fig. 13. (Note 4, 5)	-	25	32	ns
t_r	Rise Time		-	54	70	
$t_{d(off)}$	Turn-off Delay Time		-	120	157	
t_f	Fall Time		-	34	45	
Q_g	Total Gate Charge	$V_{DS} = 480V, V_{GS} = 10V, I_D = 4.0A$ see fig. 12. (Note 4, 5)	-	22	28	nC
Q_{gs}	Gate-Source Charge		-	3.2	-	
Q_{gd}	Gate-Drain Charge(Miller Charge)		-	7.8	-	

Source-Drain Diode Ratings and Characteristics

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit.
I_S	Continuous Source Current	Integral Reverse p-n Junction Diode in the MOSFET	-	-	4.0	A
I_{SM}	Pulsed Source Current		-	-	16.0	
V_{SD}	Diode Forward Voltage	$I_S = 4.0A, V_{GS} = 0V$	-	-	1.4	V
t_{rr}	Reverse Recovery Time	$I_S = 4.0A, V_{GS} = 0V, di/dt = 100A/\mu s$	-	560	-	ns
Q_{rr}	Reverse Recovery Charge		-	1.78	-	μC

NOTES

1. Repeativity rating : pulse width limited by junction temperature
2. $L = 30\text{mH}, I_{AS} = 4.0A, V_{DD} = 50V, R_G = 50$, Starting $T_J = 25^\circ\text{C}$
3. $I_{SD} = 4.0, di/dt = 300A/\mu s, V_{DD} = BV_{DSS}$, Starting $T_J = 25^\circ\text{C}$
4. Pulse Test : Pulse Width 300 μs , Duty Cycle 2%
5. Essentially independent of operating temperature.

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Fig 1. On-State Characteristics

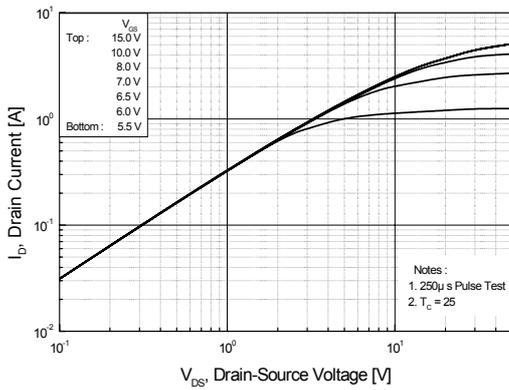


Fig 2. Transfer Characteristics

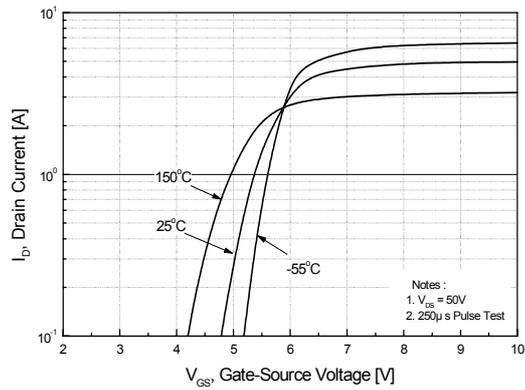


Fig 3. On Resistance Variation vs. Drain Current and Gate Voltage

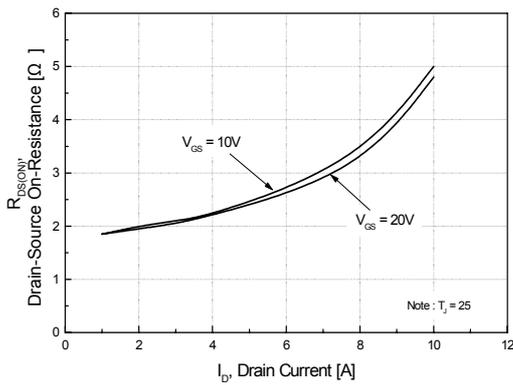


Fig 4. On State Current vs. Allowable Case Temperature

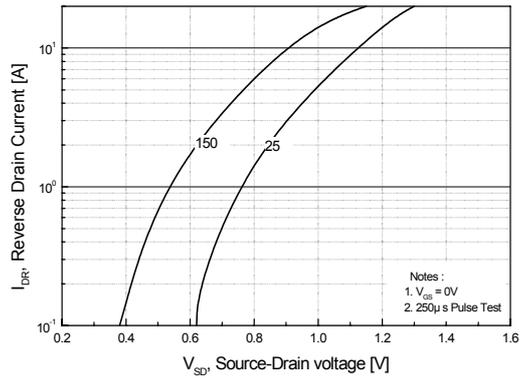


Fig 5. Capacitance Characteristics (Non-Repetitive)

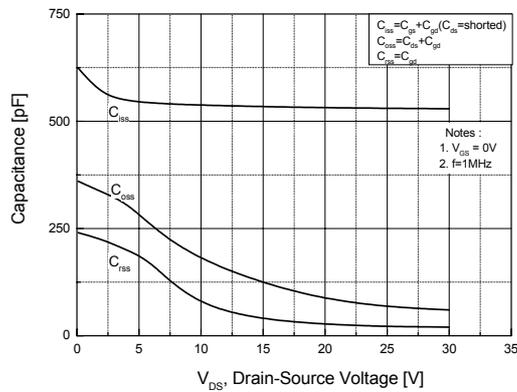
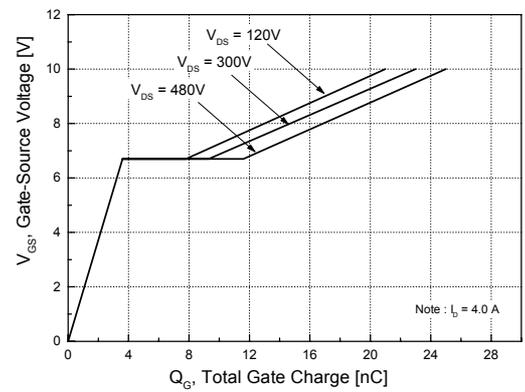


Fig 6. Gate Charge Characteristics



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Fig 7. Breakdown Voltage Variation vs. Junction Temperature

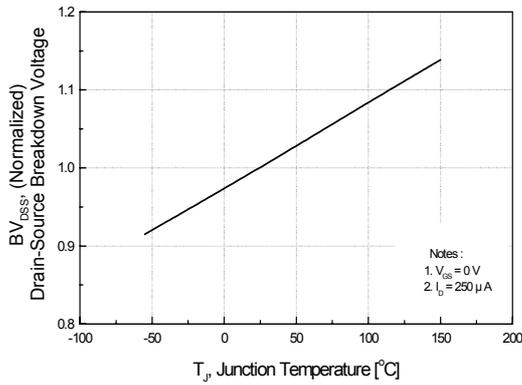


Fig 8. On-Resistance Variation vs. Junction Temperature

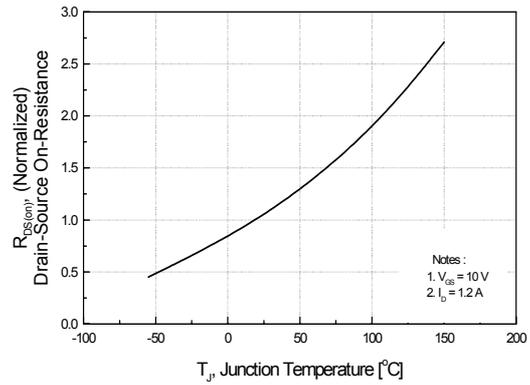


Fig 9. Maximum Safe Operating Area

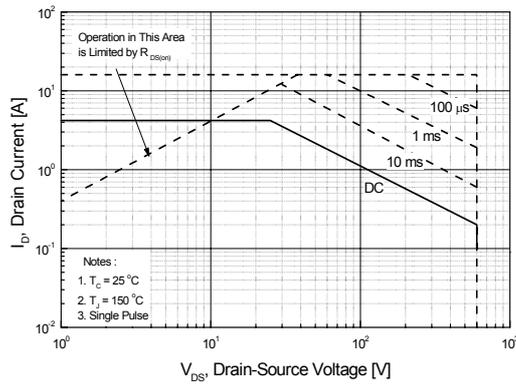


Fig 10. Maximum Drain Current vs. Case Temperature

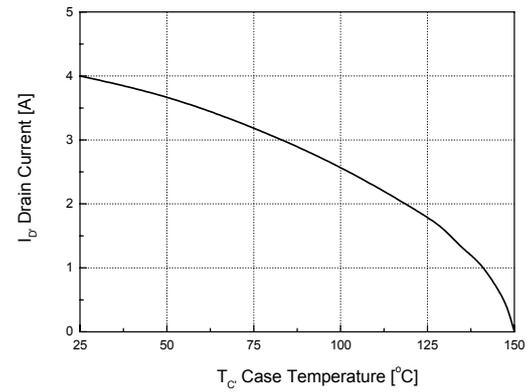
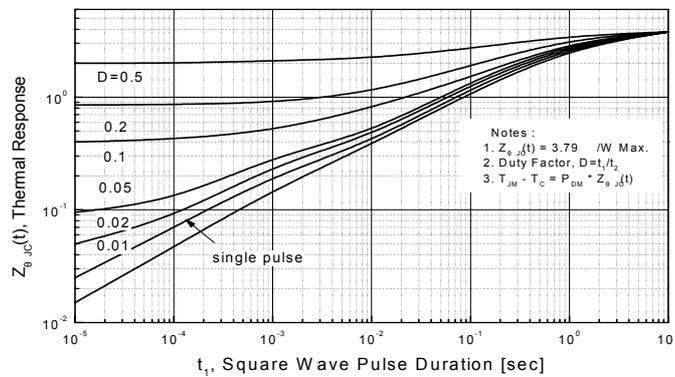


Fig 11. Transient Thermal Response Curve



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Fig. 12. Gate Charge Test Circuit & Waveforms

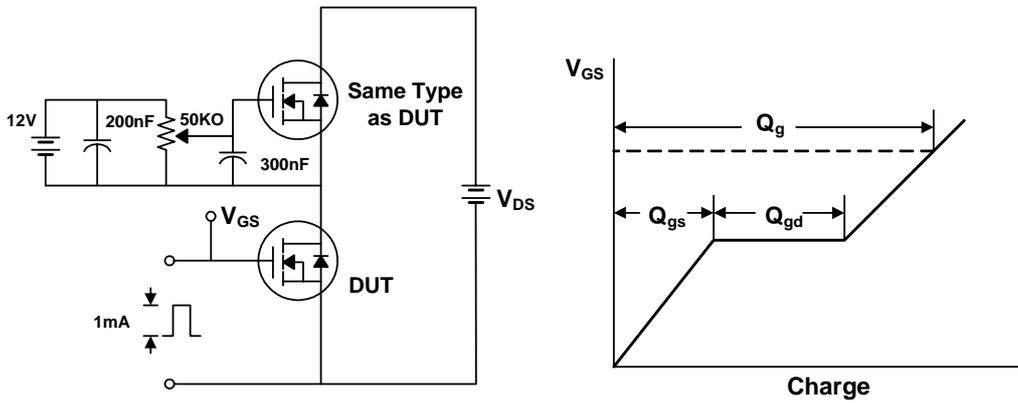


Fig 13. Switching Time Test Circuit & Waveforms

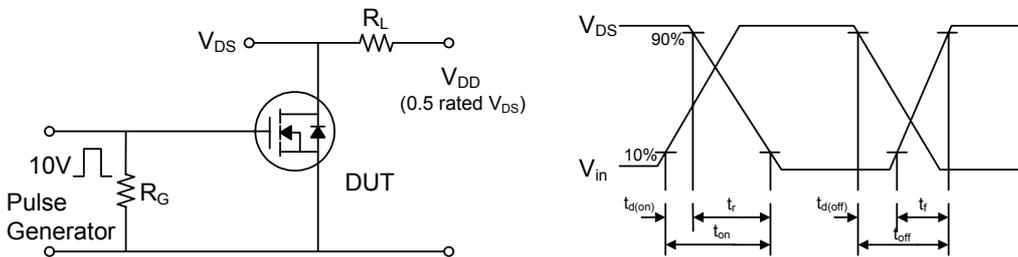
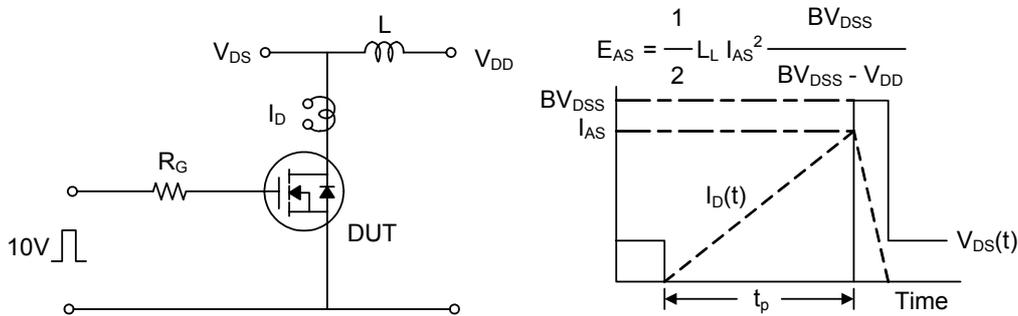
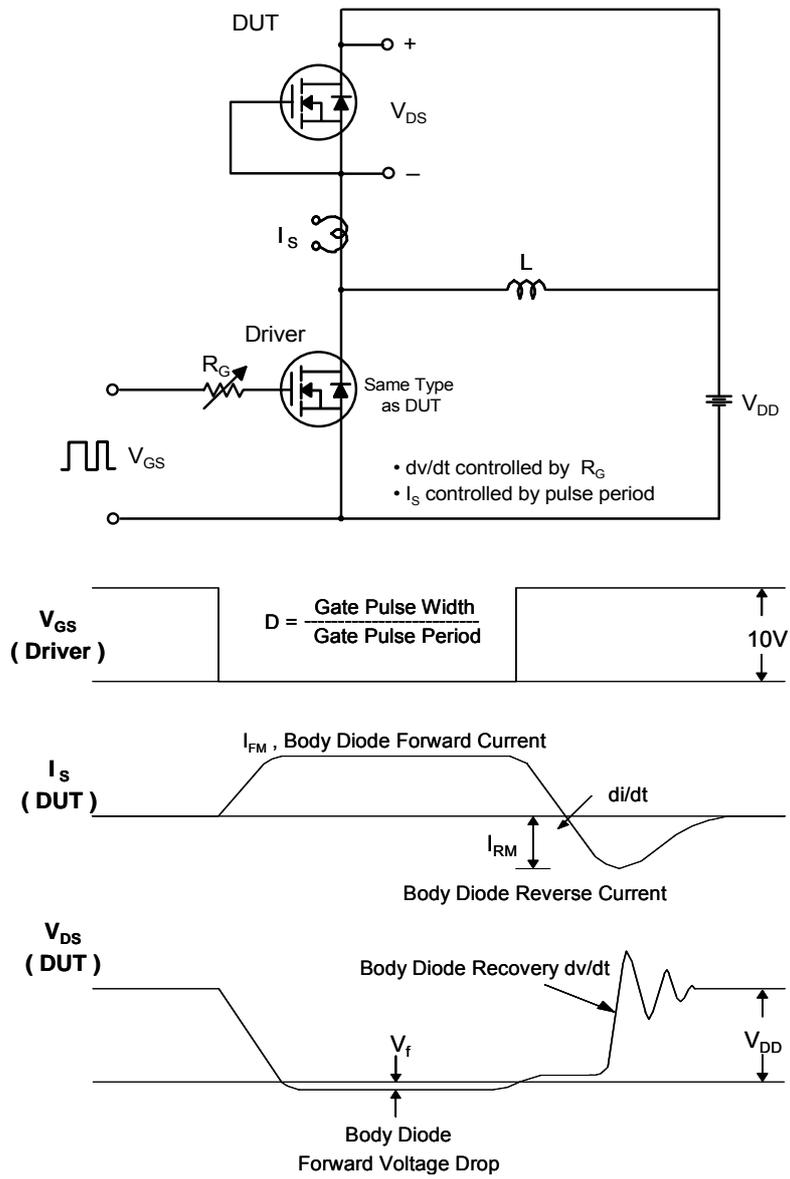


Fig 14. Unclamped Inductive Switching Test Circuit & Waveforms

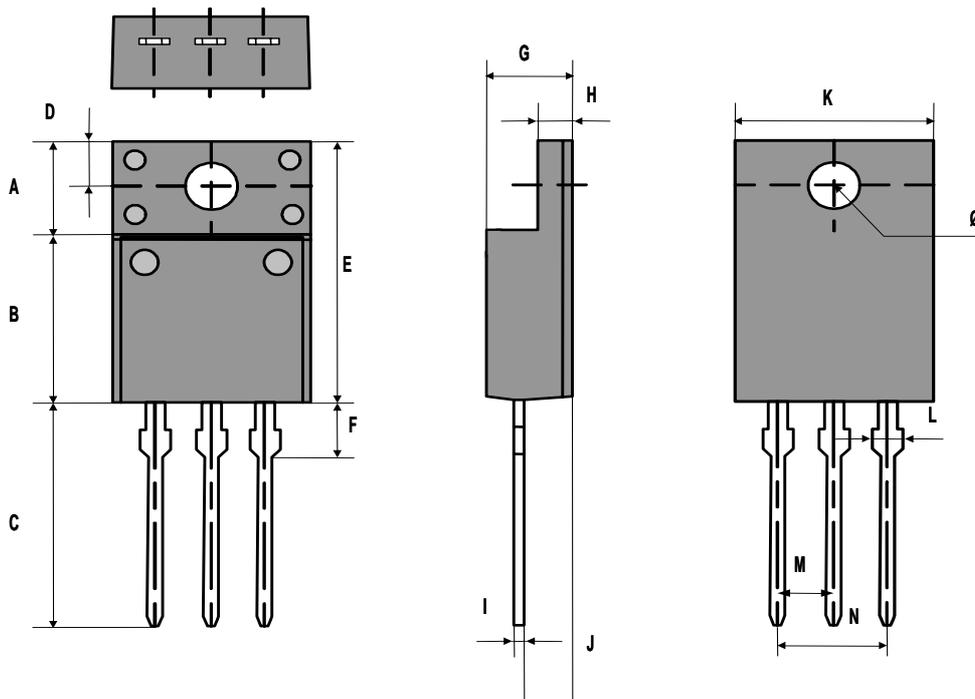


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Fig. 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms



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	Dimension [mm]				Dimension [mm]		
	Min.	Typ.	Max.		Min.	Typ.	Max.
A	6.73	6.93	7.13	I	0.55	0.59	0.65
B	7.82	8.02	8.22	J	2.26	2.46	2.66
C	13.05	13.25	13.45	K	9.00	9.50	10.0
D	2.20	2.50	2.80	L	1.10	1.50	1.90
E	14.47	14.77	15.07	M	2.47	2.57	2.67
F	2.98	3.18	3.38	N	4.94	5.04	5.14
G	4.35	4.55	4.75	Ø	3.00	3.05	3.10
H	2.96	3.06	3.16				